

PCN Number: 20190627003.1 **PCN Date:** July 1, 2019

Title: Transfer of select HV700 devices from GFAB to FFAB Wafer Fab site

Customer Contact: [PCN Manager](#) **Dept:** Quality Services

Proposed 1st Ship Date: Oct 1, 2019 **Estimated Sample Availability:** Date provided at sample request.

Change Type:

<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Assembly Materials
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification
<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>	Wafer Bump Process
<input checked="" type="checkbox"/>	Wafer Fab Site	<input checked="" type="checkbox"/>	Wafer Fab Materials	<input type="checkbox"/>	Wafer Fab Process
		<input type="checkbox"/>	Part number change		

PCN Details

Description of Change:

This change notification is to announce the transfer of select HV700 devices from GFAB to the FFAB (FR-BIP-1) Wafer Fab site for the selected devices listed in the "Product Affected" section.

Current Fab Site			New Fab Site		
Current Fab Site	Process	Wafer Diameter	New Fab Site	Process	Wafer Diameter
GFAB6	HV700	150 mm	FFAB	HV700	200 mm

Qual details are provided in the Qual Data Section.

Reason for Change:

Greenock, Scotland (GFAB) Wafer Fab site closure

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Current

Chip Site	Chip Site Origin (20L)	Chip Site Country Code (21L)	Chip Site City
GFAB6	GF6	GBR	Greenock

New Fab Site

Chip Site	Chip Site Origin (20L)	Chip Site Country Code (21L)	Chip Site City
FR-BIP-1	TID	DEU	Freising

Sample product shipping label (not actual product label)

TEXAS INSTRUMENTS
 MADE IN: Malaysia
 2DC: 2G
 MSL 2 / 260C / 1 YEAR SEAL DT
 MSL 1 / 235C / UNLIM 03/29/04
 OPT:
 ITEM: 39
LBL: 5A (L)T0:1750

(1P) SN74LS07NSR
 (Q) 2000 (D) 0336
 (31T) LOT: 3959047MLA
 (4W) TKY (1T) 7523483S12
 (P)
 (2P) REV: (V) 0033317
 (20L) CS0: SHE (21L) CCO: USA
 (22L) AS0: MLA (23L) ACC: MYS

Product Affected Group:

LM1876TF/NOPB	LM3886T/NOPB	LM3886TF/NOPB	LM4766T/NOPB
LM2876TF/NOPB	LM3886TF	LM4766T/LF15	

Qualification Report

Approve Date 24-June-2019

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: LM3886T/NOPB
AC	Autoclave, 121C	96 Hours	3/231/0
ED	Electrical Characterization	Per Datasheet Parameters	3/90/0
ELFR	Early Life Failure Rate, 125C	48 Hours	3/2400/0
HAST	Biased HAST, 130C/85%RH	96 Hours	3/231/0
HBM	ESD - HBM	3000 V	3/9/0
CDM	ESD - CDM	1000 V	3/9/0
HTOL	Life Test, 125C	1000 Hours	3/231/0
HTSL	High Temp. Storage Bake, 150C	1000 Hours	3/231/0
LU	Latch-up	(per JESD78)	3/18/0
TC	Temperature Cycle, -65/150C	500 Cycles	3231/0

- Qual Device LM3886T/NOPB is qualified at LEVEL1-260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle and HTSL as applicable.
 - The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
 - The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
 - The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles
- Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free (SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below, or you can contact your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
WW PCN Team	PCN_ww_admin_team@list.ti.com